



ISO 22007-4

# HOSTAFORM® C 13021 XAP® HOSTAFORM®

#### POM copolymer

Easy flowing Injection molding type for precision molded parts and thin-walled molded parts with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation.

Emission according to VDA 275 < 10 mg/kg

Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm.

Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances.

FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

#### Product information

Product information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
-			
Rheological properties			
Melt volume-flow rate	12	cm <sup>3</sup> /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2900	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Flexural modulus	2800	MPa	ISO 178
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	200	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	200	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30		MPa	ISO 2039-1
Poisson's ratio	0.37 <sup>[C]</sup>		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	106	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
•		` '	

Printed: 2025-05-30 Page: 1 of 7

2210 J/(kg K)

Revised: 2025-04-23 Source: Celanese Materials Database

Specific heat capacity of melt





### Flammability

Burning Behav. at 1.5mm nom. thickn.	НВ	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	yes		UL 94
FMVSS Class	В		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	41.3	mm/min	ISO 3795 (FMVSS 302)

### **Electrical properties**

· · ·		
Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	$1410 \text{ kg/m}^3$	ISO 1183

### Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

#### Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent Special characteristics Low emissions

Printed: 2025-05-30 Page: 2 of 7

Revised: 2025-04-23 Source: Celanese Materials Database





### HOSTAFORM® C 13021 XAP®

#### Additional information

Injection molding

#### Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to  $120 \, ^{\circ}\text{C}$  / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

### **Processing**

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

### Postprocessing

Conditioning e.g. moisturizing is not necessary.

**Processing Notes** 

#### **Pre-Drying**

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

#### Storage

The product can then be stored in standard conditions until processed.

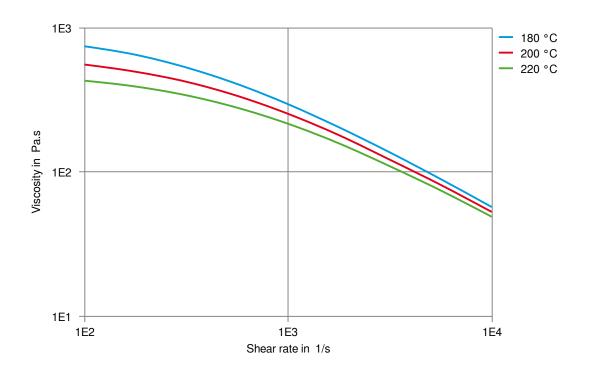
Printed: 2025-05-30 Page: 3 of 7

Revised: 2025-04-23 Source: Celanese Materials Database





Viscosity-shear rate

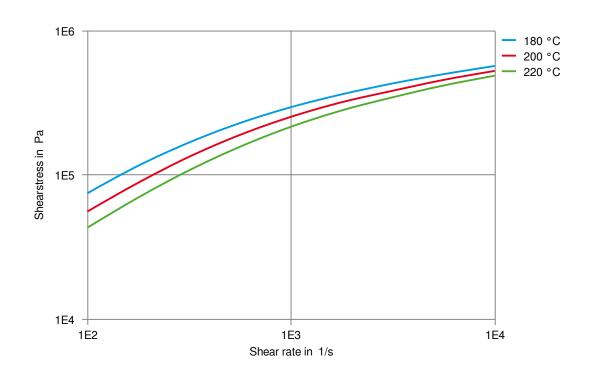


Printed: 2025-05-30 Page: 4 of 7





Shearstress-shear rate

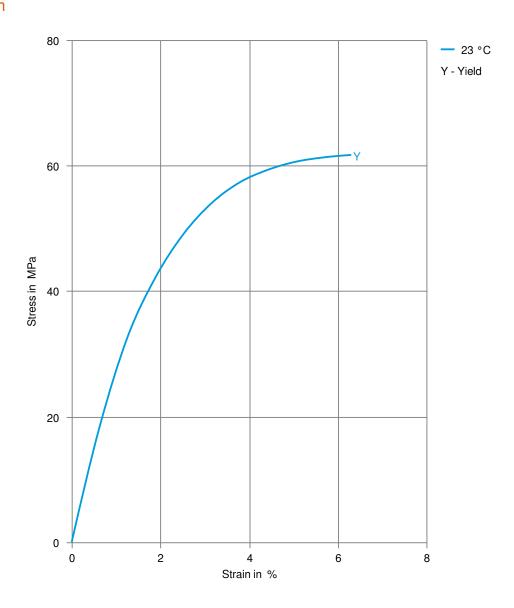


Printed: 2025-05-30 Page: 5 of 7





#### Stress-strain



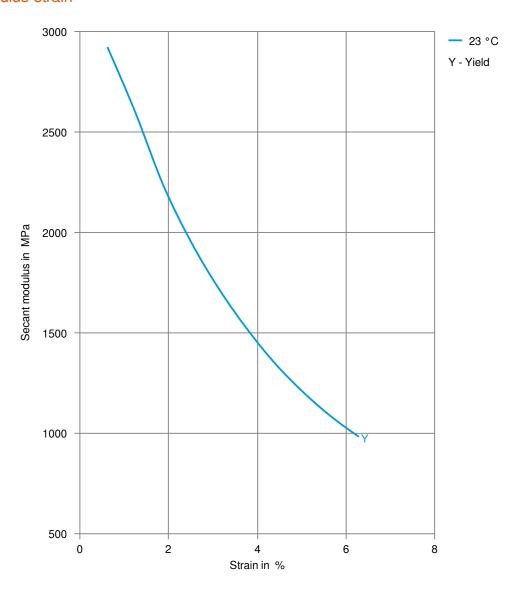
Printed: 2025-05-30 Page: 6 of 7





## HOSTAFORM® C 13021 XAP®

#### Secant modulus-strain



Printed: 2025-05-30 Page: 7 of 7

Revised: 2025-04-23 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any e

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.